ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES® INDUSTRIES®	nockburn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ion of the succession of the s	ubstances s all lowe	within the manufacture level materials for w	rer listed in which the m	em. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form 7 http://www.ipc.org/IPC-175x Distrib			 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi 				als and Mfg Information					
Supplier Information													
Company name* Company unique ID			Unique !			e ID Authority			Respons	Response Date*			
ısemi									2024-05-10				
Contact Name	act Name Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
ithorized Representative* Title - Representative				Phone - Representative*				Email - Representative*					
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item Number Mf	r Item Number	Mfr Item Name		· · · ·	Effective Date	e Version]	Manufacturing Site		Weight*	UOM	Unit Type	
NR GA	RVUS110VT3G- NO CONVERSIC		ON DESCRIPTI	ON	2024-05-10		(CNP		103.1939	mg	Each	
Manufacturing Proccess Information													
Terminal Plating / Grid Array Material	rial Terminal Base Alloy		J-STD-020 MSL	Rating	Peak Pro	Process Body Temperature Max Time at Peak		k Temperature Number of Reflow C		er of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secon	ds 3			
Comments													
level 1 - maximum time at peak temperature duri	ng soldering is 10-3	0 seconds											
For more information regarding material compos	ition please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed						
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier rise in a direct with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Su											
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the						
Supplier Digital Signature	Rastislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.2	mg	Supplier	Iron (Fe)	7439-89-6		0.0082	mg
			Supplier	Copper (Cu)	7440-50-8		8.1893	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0025	mg
Die	0.8039	mg	Supplier	Silicon (Si)	7440-21-3		0.7959	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.008	mg
Die Attach Solder	1.62	mg	Supplier	Silver (Ag)	7440-22-4		0.0405	mg
			А	Lead (Pb)	7439-92-1	7a	1.4985	mg
			Supplier	Tin (Sn)	7440-31-5		0.081	mg
Lead Frame	33.6	mg	Supplier	Iron (Fe)	7439-89-6		0.0336	mg
			Supplier	Copper (Cu)	7440-50-8		33.5563	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0101	mg
Mold Compound-Black	55.19	mg	Supplier	Polycondensate of 4,4'- bis(methoxymethyl)biphenyl and phenol	205830-20-2		1.3798	mg
			Supplier	Triphenylphosphine	603-35-0		0.2759	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.2759	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		0.2759	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5519	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.671	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.7595	mg
Plating	3.78	mg	Supplier	Tin (Sn)	7440-31-5		3.78	mg